Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	ARM® Cortex®-M0, ARM® Cortex®-M4
Core Size	32-Bit Dual-Core
Speed	204MHz
Connectivity	CANbus, EBI/EMI, I²C, IrDA, Microwire, MMC/SD, SPI, SSI, SSP, UART/USART, USB, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, Motor Control PWM, POR, PWM, WDT
Number of I/O	83
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	200K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 8x10b SAR; D/A 1x10b
Oscillator Type	External, Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc43s20fbd144e

Table 3. Pin description *…continued*

LCD, Ethernet, USB0, and USB1 functions are not available on all parts. See Table 2.

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P3_4	A15	C14	B8	119	[2]	N; PU	I/O	**GPIO1[14] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SPIFI_SIO3 —** I/O lane 3 for SPIFI.
							O	**U1_TXD —** Transmitter output for UART 1.
							I/O	**I2S0_TX_WS —** Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I²S-bus specification*.
							I/O	**I2S1_RX_SDA —** I2S1 Receive data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the *I²S-bus specification*.
							O	**LCD_VD13 —** LCD data.
P3_5	C12	C11	B7	121	[2]	N; PU	I/O	**GPIO1[15] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SPIFI_SIO2 —** I/O lane 2 for SPIFI.
							I	**U1_RXD —** Receiver input for UART 1.
							I/O	**I2S0_TX_SDA —** I2S transmit data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the *I²S-bus specification*.
							I/O	**I2S1_RX_WS —** Receive Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I²S-bus specification*.
							O	**LCD_VD12 —** LCD data.
P3_6	B13	B12	C7	122	[2]	N; PU	I/O	**GPIO0[6] —** General purpose digital input/output pin.
							I/O	**SPI_MISO —** Master In Slave Out for SPI.
							I/O	**SSP0_SSEL —** Slave Select for SSP0.
							I/O	**SPIFI_MISO —** Input 1 in SPIFI quad mode; SPIFI output IO1.
							-	**R —** Function reserved.
							I/O	**SSP0_MISO —** Master In Slave Out for SSP0.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P3_7	C11	C10	D7	123	[2]	N; PU	-	**R —** Function reserved.
							I/O	**SPI_MOSI —** Master Out Slave In for SPI.
							I/O	**SSP0_MISO —** Master In Slave Out for SSP0.
							I/O	**SPIFI_MOSI —** Input I0 in SPIFI quad mode; SPIFI output IO0.
							I/O	**GPIO5[10] —** General purpose digital input/output pin.
							I/O	**SSP0_MOSI —** Master Out Slave in for SSP0.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

LCD, Ethernet, USB0, and USB1 functions are not available on all parts. See Table 2.

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P9_6	L11	M9	-	72	[2]	N; PU	I/O	**GPIO4[11] —** General purpose digital input/output pin.
							O	**MCOB1 —** Motor control PWM channel 1, output B.
							I	**USB1_PWR_FAULT —** USB1 Port power fault signal indicating over-current condition; this signal monitors over-current on the USB1 bus (external circuitry required to detect over-current condition).
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**ENET_COL —** Ethernet Collision detect (MII interface).
							I/O	**SGPIO8 —** General purpose digital input/output pin.
							I	**U0_RXD —** Receiver input for USART0.
PA_0	L12	L10	-	-	[2]	N; PU	-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**I2S1_RX_MCLK —** I2S1 receive master clock.
							O	**CGU_OUT1 —** CGU spare clock output 1.
							-	**R —** Function reserved.
PA_1	J14	H12	-	-	[3]	N; PU	I/O	**GPIO4[8] —** General purpose digital input/output pin.
							I	**QEI_IDX —** Quadrature Encoder Interface INDEX input.
							-	**R —** Function reserved.
							O	**U2_TXD —** Transmitter output for USART2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PA_2	K15	J13	-	-	[3]	N; PU	I/O	**GPIO4[9] —** General purpose digital input/output pin.
							I	**QEI_PHB —** Quadrature Encoder Interface PHB input.
							-	**R —** Function reserved.
							I	**U2_RXD —** Receiver input for USART2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

LCD, Ethernet, USB0, and USB1 functions are not available on all parts. See Table 2.

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PC_3	F5	-	-	-	[5]	N; PU	I/O	**USB1_ULPI_D5 —** ULPI link bidirectional data line 5.
							-	**R —** Function reserved.
							O	**U1_RTS —** Request to Send output for UART 1. Can also be configured to be an RS-485/EIA-485 output enable signal for UART 1.
							O	**ENET_TXD3 —** Ethernet transmit data 3 (MII interface).
							I/O	**GPIO6[2] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**SD_VOLT1 —** SD/MMC bus voltage select output 1.
							AI	**ADC1_0 —** DAC output; ADC1 and ADC0, input channel 0. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.
PC_4	F4	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							I/O	**USB1_ULPI_D4 —** ULPI link bidirectional data line 4.
							-	**R —** Function reserved.
								ENET_TX_EN — Ethernet transmit enable (RMII/MII interface).
							I/O	**GPIO6[3] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							I	**T3_CAP1 —** Capture input 1 of timer 3.
							I/O	**SD_DAT0 —** SD/MMC data bus line 0.
PC_5	G4	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							I/O	**USB1_ULPI_D3 —** ULPI link bidirectional data line 3.
							-	**R —** Function reserved.
							O	**ENET_TX_ER —** Ethernet Transmit Error (MII interface).
							I/O	**GPIO6[4] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							I	**T3_CAP2 —** Capture input 2 of timer 3.
							I/O	**SD_DAT1 —** SD/MMC data bus line 1.
PC_6	H6	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							I/O	**USB1_ULPI_D2 —** ULPI link bidirectional data line 2.
							-	**R —** Function reserved.
							I	**ENET_RXD2 —** Ethernet receive data 2 (MII interface).
							I/O	**GPIO6[5] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							I	**T3_CAP3 —** Capture input 3 of timer 3.
							I/O	**SD_DAT2 —** SD/MMC data bus line 2.

Table 3. Pin description *…continued*

LCD, Ethernet, USB0, and USB1 functions are not available on all parts. See Table 2.

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PD_0	N2	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_15 —** SCTimer/PWM output 15. Match output 3 of timer 3.
							O	**EMC_DQMOUT2 —** Data mask 2 used with SDRAM and static devices.
							-	**R —** Function reserved.
							I/O	**GPIO6[14] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SGPIO4 —** General purpose digital input/output pin.
PD_1	P1	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**EMC_CKEOUT2 —** SDRAM clock enable 2.
							-	**R —** Function reserved.
							I/O	**GPIO6[15] —** General purpose digital input/output pin.
							O	**SD_POW —** SD/MMC power monitor output.
							-	**R —** Function reserved.
							I/O	**SGPIO5 —** General purpose digital input/output pin.
PD_2	R1	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_7 —** SCTimer/PWM output 7. Match output 3 of timer 1.
							I/O	**EMC_D16 —** External memory data line 16.
							-	**R —** Function reserved.
							I/O	**GPIO6[16] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SGPIO6 —** General purpose digital input/output pin.
PD_3	P4	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_6 —** SCTimer/PWM output 7. Match output 2 of timer 1.
							I/O	**EMC_D17 —** External memory data line 17.
							-	**R —** Function reserved.
							I/O	**GPIO6[17] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SGPIO7 —** General purpose digital input/output pin.

Table 3. Pin description *…continued*

LCD, Ethernet, USB0, and USB1 functions are not available on all parts. See Table 2.

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PF_6	E7	-	-	-	[5]	N; PU	-	**R —** Function reserved.
							I/O	**U3_DIR —** RS-485/EIA-485 output enable/direction control for USART3.
							I/O	**SSP1_MISO —** Master In Slave Out for SSP1.
							O	**TRACEDATA[1] —** Trace data, bit 1.
							I/O	**GPIO7[20] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							I/O	**SGPIO5 —** General purpose digital input/output pin.
							I/O	**I2S1_TX_SDA —** I2S1 transmit data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the *I²S-bus specification*.
							AI	**ADC1_3 —** ADC1 and ADC0, input channel 3. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.
PF_7	B7	-	-	-	[5]	N; PU	-	**R —** Function reserved.
							I/O	**U3_BAUD —** Baud pin for USART3.
							I/O	**SSP1_MOSI —** Master Out Slave in for SSP1.
							O	**TRACEDATA[2] —** Trace data, bit 2.
							I/O	**GPIO7[21] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							I/O	**SGPIO6 —** General purpose digital input/output pin.
							I/O	**I2S1_TX_WS —** Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I²S-bus specification*.
							AI/O	**ADC1_7 —** ADC1 and ADC0, input channel 7 or band gap output. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.
PF_8	E6	-	-	-	[5]	N; PU	-	**R —** Function reserved.
							I/O	**U0_UCLK —** Serial clock input/output for USART0 in synchronous mode.
							I	**CTIN_2 —** SCTimer/PWM input 2. Capture input 2 of timer 0.
							O	**TRACEDATA[3] —** Trace data, bit 3.
							I/O	**GPIO7[22] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							I/O	**SGPIO7 —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							AI	**ADC0_2 —** ADC0 and ADC1, input channel 2. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.

Table 3. Pin description *…continued*

LCD, Ethernet, USB0, and USB1 functions are not available on all parts. See Table 2.

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
Clock pins								
CLK0	N5	M4	K3	45	[4]	O; PU	O	**EMC_CLK0 —** SDRAM clock 0.
							O	**CLKOUT —** Clock output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SD_CLK —** SD/MMC card clock.
							O	**EMC_CLK01 —** SDRAM clock 0 and clock 1 combined.
							I/O	**SSP1_SCK —** Serial clock for SSP1.
							I	**ENET_TX_CLK (ENET_REF_CLK) —** Ethernet Transmit Clock (MII interface) or Ethernet Reference Clock (RMII interface).
CLK1	T10	-	-	-	[4]	O; PU	O	**EMC_CLK1 —** SDRAM clock 1.
							O	**CLKOUT —** Clock output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**CGU_OUT0 —** CGU spare clock output 0.
							-	**R —** Function reserved.
							O	**I2S1_TX_MCLK —** I2S1 transmit master clock.
CLK2	D14	P10	K6	99	[4]	O; PU	O	**EMC_CLK3 —** SDRAM clock 3.
							O	**CLKOUT —** Clock output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SD_CLK —** SD/MMC card clock.
							O	**EMC_CLK23 —** SDRAM clock 2 and clock 3 combined.
							O	**I2S0_TX_MCLK —** I2S transmit master clock.
							I/O	**I2S1_RX_SCK —** Receive Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the I^2S-bus specification.
CLK3	P12	-	-	-	[4]	O; PU	O	**EMC_CLK2 —** SDRAM clock 2.
							O	**CLKOUT —** Clock output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**CGU_OUT1 —** CGU spare clock output 1.
							-	**R —** Function reserved.
							I/O	**I2S1_RX_SCK —** Receive Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the I^2S-bus specification.

7.6.1 Features

- Controls system exceptions and peripheral interrupts.
- The Cortex-M4 NVIC supports up to 53 vectored interrupts.
- Eight programmable interrupt priority levels with hardware priority level masking.
- Relocatable vector table.
- Non-Maskable Interrupt (NMI).
- Software interrupt generation.

7.6.2 Interrupt sources

Each peripheral device has one interrupt line connected to the NVIC but may have several interrupt flags. Individual interrupt flags can represent more than one interrupt source.

7.7 System Tick timer (SysTick)

The ARM Cortex-M4 includes a system tick timer (SysTick) that is intended to generate a dedicated SYSTICK exception at a 10 ms interval.

Remark: The SysTick is not included in the ARM Cortex-M0 core.

7.8 Event router

The event router combines various internal signals, interrupts, and the external interrupt pins (WAKEUP[3:0]) to create an interrupt in the NVIC, if enabled. In addition, the event router creates a wake-up signal to the ARM core and the CCU for waking up from Sleep, Deep-sleep, Power-down, and Deep power-down modes. Individual events can be configured as edge or level sensitive and can be enabled or disabled in the event router. The event router can be battery powered.

The following events if enabled in the event router can create a wake-up signal from sleep, deep-sleep, power-down, and deep power-down modes and/or create an interrupt:

- External pins WAKEUP0/1/2/3 and $\overline{\text{RESET}}$
- Alarm timer, RTC (32 kHz oscillator running)

The following events if enabled in the event router can create a wake-up signal from sleep mode only and/or create an interrupt:

- WWDT, BOD interrupts
- C_CAN0/1 and QEI interrupts
- Ethernet, USB0, USB1 signals
- Selected outputs of combined timers (SCTimer/PWM and timer0/1/3)

Remark: Any interrupt can wake up the ARM Cortex-M4 from sleep mode if enabled in the NVIC.

7.9 Global Input Multiplexer Array (GIMA)

The GIMA routes signals to event-driven peripheral targets like the SCTimer/PWM, timers, event router, or the ADCs.

7.18.5 I²C-bus interface

Remark: The LPC43S50/S30/S20 contain two I²C-bus interfaces.

The I²C-bus is bidirectional for inter-IC control using only two wires: a Serial Clock line (SCL) and a Serial Data line (SDA). Each device is recognized by a unique address and can operate as either a receiver-only device (for example an LCD driver) or a transmitter with the capability to both receive and send information (such as memory). Transmitters and/or receivers can operate in either master or slave mode, depending on whether the chip has to initiate a data transfer or is only addressed. The I²C is a multi-master bus and can be controlled by more than one bus master connected to it.

7.18.5.1 Features

- I²C0 is a standard I²C-compliant bus interface with open-drain pins. I²C0 also supports Fast mode plus with bit rates up to 1 Mbit/s.
- I²C1 uses standard I/O pins with bit rates of up to 400 kbit/s (Fast I²C-bus).
- Easy to configure as master, slave, or master/slave.
- Programmable clocks allow versatile rate control.
- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I²C-bus can be used for test and diagnostic purposes.
- All I²C-bus controllers support multiple address recognition and a bus monitor mode.

7.18.6 I²S interface

Remark: The LPC43S50/S30/S20 contain two I²S-bus interfaces.

The I²S-bus provides a standard communication interface for digital audio applications.

The *I²S-bus specification* defines a 3-wire serial bus using one data line, one clock line, and one word select signal. The basic I²S-bus connection has one master, which is always the master, and one slave. The I²S-bus interface provides a separate transmit and receive channel, each of which can operate as either a master or a slave.

7.18.6.1 Features

- The I²S interface has separate input/output channels, each of which can operate in master or slave mode.
- Capable of handling 8-bit, 16-bit, and 32-bit word sizes.
- Mono and stereo audio data supported.
- The sampling frequency can range from 16 kHz to 192 kHz (16, 22.05, 32, 44.1, 48, 96, 192) kHz.
- Support for an audio master clock.

10. Static characteristics

Table 10. Static characteristics

T_{amb} = −40 °C to +85 °C, unless otherwise specified.

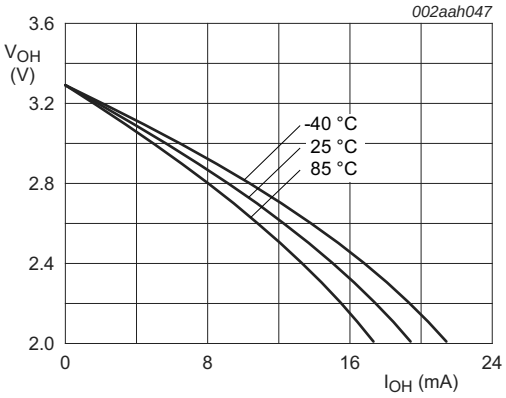
Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
Supply pins							
$V_{DD(IO)}$	input/output supply voltage			2.2	-	3.6	V
$V_{DD(REG)(3V3)}$	regulator supply voltage (3.3 V)		[2]	2.2	-	3.6	V
$V_{DDA(3V3)}$	analog supply voltage (3.3 V)	on pin VDDA		2.2	-	3.6	V
		on pins USB0_VDDA3V3_ DRIVER and USB0_VDDA3V3		3.0	3.3	3.6	V
V_{BAT}	battery supply voltage		[2]	2.2	-	3.6	V
$V_{prog(pf)}$	polyfuse programming voltage	on pin VPP (for OTP)	[3]	2.7	-	3.6	V
$I_{prog(pf)}$	polyfuse programming current	on pin VPP; OTP programming time ≤ 1.6 ms		-	-	30	mA
$I_{DD(REG)(3V3)}$	regulator supply current (3.3 V)	Active mode; M0-core in reset; code `while(1){}` executed from RAM; all peripherals disabled; PLL1 enabled					
		CCLK = 12 MHz	[4]	-	6.6	-	mA
		CCLK = 60 MHz	[4]		25.3	-	mA
		CCLK = 120 MHz	[4]	-	48.4	-	mA
		CCLK = 180 MHz	[4]	-	72.0	-	mA
		CCLK = 204 MHz	[4]	-	81.5	-	mA
$I_{DD(REG)(3V3)}$	regulator supply current (3.3 V)	after WFE/WFI instruction executed from RAM; all peripherals disabled; M0 core in reset					
		sleep mode	[4][5]	-	5.0	-	mA
		deep-sleep mode	[4]	-	30	-	µA
		power-down mode	[4]	-	15	-	µA
		deep power-down mode	[4][6]	-	0.03	-	µA
		deep power-down mode; VBAT floating	[4]-	-	2	-	µA
I_{BAT}	battery supply current	active mode; V_{BAT} = 3.2 V; $V_{DD(REG)(3V3)}$ = 3.6 V.	[7]	-	0	-	nA

Table 10. Static characteristics *…continued*
T_{amb} = −40 °C to +85 °C, unless otherwise specified.

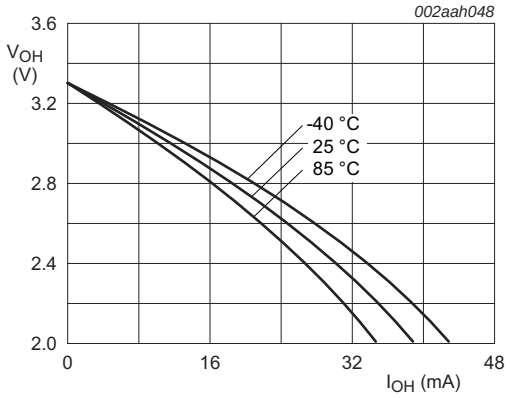
Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
I_{LI}	input leakage current	$V_I = V_{DD(IO)}$	[13]	-	4.5	-	μA
		V_I = 5 V		-	-	10	μA
Oscillator pins							
$V_{i(XTAL1)}$	input voltage on pin XTAL1			−0.5	-	1.2	V
$V_{o(XTAL2)}$	output voltage on pin XTAL2			−0.5	-	1.2	V
C_{io}	input/output capacitance		[17]	-	-	0.8	pF
USB0 pins[18]							
V_I	input voltage	on pins USB0_DP; USB0_DM; USB0_VBUS					
		$V_{DD(IO)} \geq 2.2$ V		0	-	5.25	V
		$V_{DD(IO)}$ = 0 V		0	-	3.6	V
R_{pd}	pull-down resistance	on pin USB0_VBUS		48	64	80	kΩ
V_{IC}	common-mode input voltage	high-speed mode		−50	200	500	mV
		full-speed/low-speed mode		800	-	2500	mV
		chirp mode		−50	-	600	mV
$V_{i(dif)}$	differential input voltage			100	400	1100	mV
USB1 pins (USB1_DP/USB1_DM)[18]							
I_{OZ}	OFF-state output current	0 V < V_I < 3.3 V	[18]	-	-	±10	μA
V_{BUS}	bus supply voltage		[19]	-	-	5.25	V
V_{DI}	differential input sensitivity voltage	|(D+) − (D−)|		0.2	-	-	V
V_{CM}	differential common mode voltage range	includes V_{DI} range		0.8	-	2.5	V
$V_{th(rs)se}$	single-ended receiver switching threshold voltage			0.8	-	2.0	V
V_{OL}	LOW-level output voltage for low-/full-speed	R_L of 1.5 kΩ to 3.6 V		-	-	0.18	V
V_{OH}	HIGH-level output voltage (driven) for low-/full-speed	R_L of 15 kΩ to GND		2.8	-	3.5	V
C_{trans}	transceiver capacitance	pin to GND		-	-	20	pF
Z_{DRV}	driver output impedance for driver which is not high-speed capable	with 33 Ω series resistor; steady state drive	[20]	36	-	44.1	Ω

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

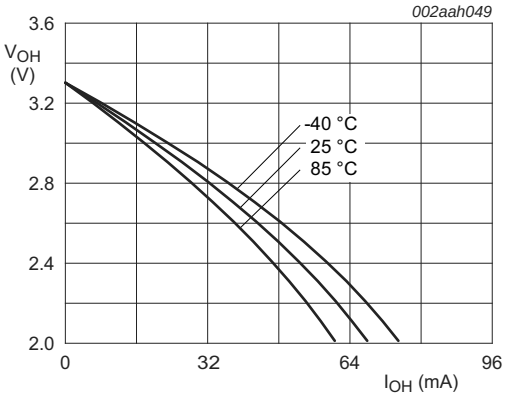
[2] The recommended operating condition for the battery supply is $V_{DD(REG)(3V3)} > V_{BAT}$ + 0.2 V. See Figure 18.



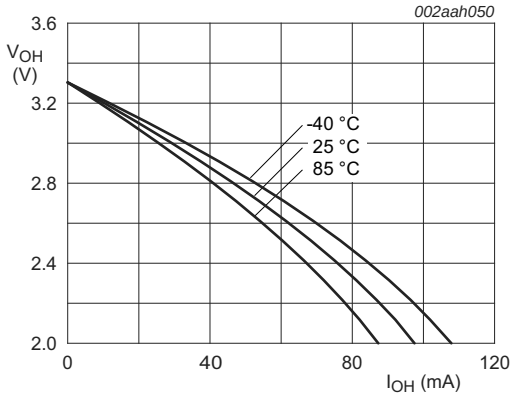
Conditions: $V_{DD(REG)(3V3)} = V_{DD(IO)} = 3.3$ V; normal-drive; EHD = 0x0.



Conditions: $V_{DD(REG)(3V3)} = V_{DD(IO)} = 3.3$ V; medium-drive; EHD = 0x1.



Conditions: $V_{DD(REG)(3V3)} = V_{DD(IO)} = 3.3$ V; high-drive; EHD = 0x2.



Conditions: $V_{DD(REG)(3V3)} = V_{DD(IO)} = 3.3$ V; ultra high-drive; EHD = 0x3.

Fig 23. High-drive pins; typical HIGH level output voltage V_{OH} versus HGH level output current I_{OH}

11.11 SSP interface

Table 24. Dynamic characteristics: SSP pins in SPI mode

T_{amb} = −40 °C to +85 °C; 2.2 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V; C_L = 20 pF. Sampled at 10 % and 90 % of the signal level; EHS = 1 for all pins. Simulated values.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
SSP master							
$T_{cy(clk)}$	clock cycle time	full-duplex mode	[1]	$1/(25.5 \times 10^6)$	-	-	s
		when only transmitting		$1/(51 \times 10^6)$	-	-	s
t_{DS}	data set-up time	in SPI mode		13.6	-	-	ns
t_{DH}	data hold time	in SPI mode		−3.8	-	-	ns
$t_{v(Q)}$	data output valid time	in SPI mode		-	-	6.0	ns
$t_{h(Q)}$	data output hold time	in SPI mode		−1.1	-	-	ns
t_{lead}	lead time	continuous transfer mode SPI mode; CPOL = 0; CPHA = 0		$T_{cy(clk)} + 3.2$	-	$T_{cy(clk)} + 6.1$	ns
		SPI mode; CPOL = 0; CPHA = 1		$0.5 \times T_{cy(clk)} + 3.2$	-	$0.5 \times T_{cy(clk)} + 6.1$	ns
		SPI mode; CPOL = 1; CPHA = 0		$T_{cy(clk)} + 3.2$	-	$T_{cy(clk)} + 6.1$	ns
		SPI mode; CPOL = 1; CPHA = 1		$0.5 \times T_{cy(clk)} + 3.2$	-	$0.5 \times T_{cy(clk)} + 6.1$	ns
		synchronous serial frame mode		$0.5 \times T_{cy(clk)} + 3.2$	-	$0.5 \times T_{cy(clk)} + 6.1$	ns
		microwire frame format		$T_{cy(clk)} + 3.2$	-	$T_{cy(clk)} + 6.1$	ns
t_{lag}	lag time	continuous transfer mode SPI mode; CPOL = 0; CPHA = 0		$0.5 \times T_{cy(clk)}$	-	-	ns
		SPI mode; CPOL = 0; CPHA = 1		$T_{cy(clk)}$	-	-	ns
		SPI mode; CPOL = 1; CPHA = 0		$0.5 \times T_{cy(clk)}$	-	-	ns
		SPI mode; CPOL = 1; CPHA = 1		$T_{cy(clk)}$	-	-	ns
		synchronous serial frame mode		$T_{cy(clk)}$	-	-	ns
		microwire frame format		$0.5 \times T_{cy(clk)}$	-	-	ns

11.12 SPI interface

Table 25. Dynamic characteristics: SPI

T_{amb} = −40 °C to +85 °C; 2.2 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V. Simulated values.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$T_{cy(PCLK)}$	PCLK cycle time			5			ns
$T_{cy(clk)}$	clock cycle time		[1]	40	-	-	ns
Master							
t_{DS}	data set-up time			7.2	-	-	ns
t_{DH}	data hold time			0	-	-	ns
$t_{v(Q)}$	data output valid time			-	-	3.7	ns
$t_{h(Q)}$	data output hold time			-	-	1.2	ns
Slave							
t_{DS}	data set-up time			1.2	-	-	ns
t_{DH}	data hold time			3 x $T_{cy(PCLK)}$ + 0.54	-	-	ns
$t_{v(Q)}$	data output valid time			-	-	3 x $T_{cy(PCLK)}$ + 9.7	ns
$t_{h(Q)}$	data output hold time			-	-	2 x $T_{cy(PCLK)}$ + 7.1	ns

[1] $T_{cy(clk)}$ = 8/BASE_SPI_CLK. Tcy(PCLK) = 1/BASE_SPI_CLK.

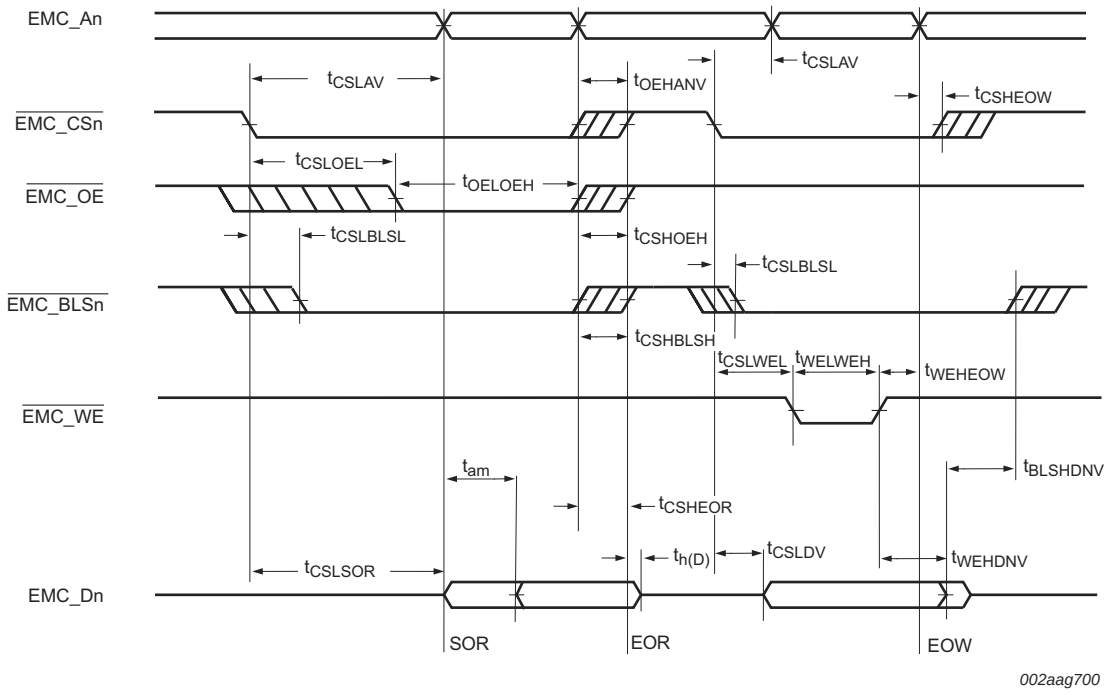


Fig 35. External static memory read/write access (PB = 1)

11.16 USB interface

Table 30. Dynamic characteristics: USB0 and USB1 pins (full-speed)
C_L = 50 pF; R_{pu} = 1.5 kΩ on D+ to $V_{DD(IO)}$; 3.0 V ≤ $V_{DD(IO)}$ ≤ 3.6 V.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
t_r	rise time	10 % to 90 %		4	-	20	ns
t_f	fall time	10 % to 90 %		4	-	20	ns
t_{FRFM}	differential rise and fall time matching	t_r / t_f		90	-	111.11	%
V_{CRS}	output signal crossover voltage			1.3	-	2.0	V
t_{FEOPT}	source SE0 interval of EOP	see Figure 37		160	-	175	ns
t_{FDEOP}	source jitter for differential transition to SE0 transition	see Figure 37		−2	-	+5	ns
t_{JR1}	receiver jitter to next transition			−18.5	-	+18.5	ns
t_{JR2}	receiver jitter for paired transitions	10 % to 90 %		−9	-	+9	ns
t_{EOPR1}	EOP width at receiver	must reject as EOP; see Figure 37	[1]	40	-	-	ns
t_{EOPR2}	EOP width at receiver	must accept as EOP; see Figure 37	[1]	82	-	-	ns

[1] Characterized but not implemented as production test. Guaranteed by design.

Remark: If only USB0 (HS USB) is used, the pins VDDREG and VDDIO can be at different voltages within the operating range but should have the same ramp up time. If USB1(FS USB) is used, the pins VDDREG and VDDIO should be a minimum of 3.0 V and be tied together.

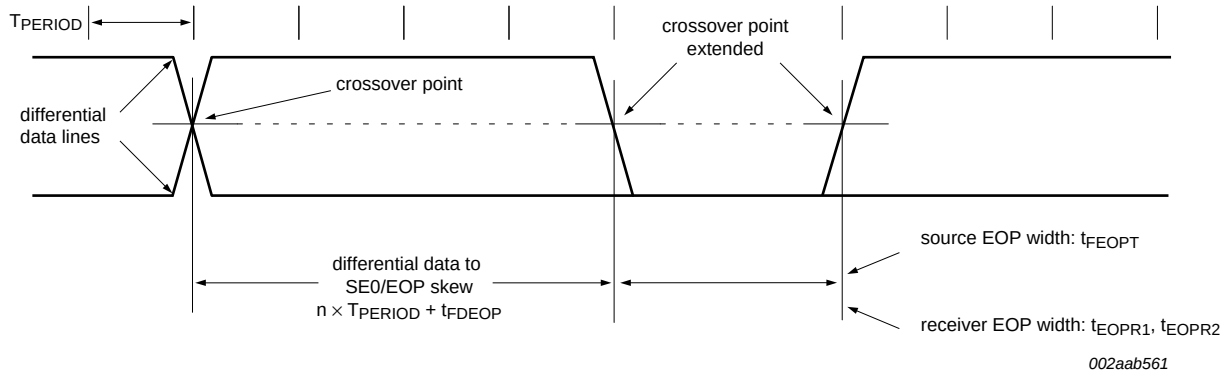


Fig 37. Differential data-to-EOP transition skew and EOP width

Table 31. Static characteristics: USB0 PHY pins[1]

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
High-speed mode							
P_{cons}	power consumption		[2]	-	68	-	mW
$I_{DDA(3V3)}$	analog supply current (3.3 V)	on pin USB0_VDDA3V3_DRIVER; total supply current	[3]	-	18	-	mA
		during transmit		-	31	-	mA
		during receive		-	14	-	mA
		with driver tri-stated		-	14	-	mA
I_{DDD}	digital supply current			-	7	-	mA
Full-speed/low-speed mode							
P_{cons}	power consumption		[2]	-	15	-	mW
$I_{DDA(3V3)}$	analog supply current (3.3 V)	on pin USB0_VDDA3V3_DRIVER; total supply current		-	3.5	-	mA
		during transmit		-	5	-	mA
		during receive		-	3	-	mA
		with driver tri-stated		-	3	-	mA
I_{DDD}	digital supply current			-	3	-	mA
Suspend mode							
$I_{DDA(3V3)}$	analog supply current (3.3 V)			-	24	-	μA
		with driver tri-stated		-	24	-	μA
		with OTG functionality enabled		-	3	-	mA
I_{DDD}	digital supply current			-	30	-	μA
VBUS detector outputs							
V_{th}	threshold voltage	for VBUS valid		4.4	-	-	V
		for session end		0.2	-	0.8	V
		for A valid		0.8	-	2	V
		for B valid		2	-	4	V
V_{hys}	hysteresis voltage	for session end		-	150	10	mV
		A valid		-	200	10	mV
		B valid		-	200	10	mV

[1] Characterized but not implemented as production test.

[2] Total average power consumption.

[3] The driver is active only 20 % of the time.

11.17 Ethernet

Remark: The timing characteristics of the ENET_MDC and ENET_MDIO signals comply with the *IEEE standard 802.3*.

Table 39. LCD panel connections for STN dual panel mode *…continued*

External pin	4-bit mono STN dual panel		8-bit mono STN dual panel		Color STN dual panel	
	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function
LCD_VD2	P4_3	UD[2]	P4_3	UD[2]	P4_3	UD[2]
LCD_VD1	P4_4	UD[1]	P4_4	UD[1]	P4_4	UD[1]
LCD_VD0	P4_1	UD[0]	P4_1	UD[0]	P4_1	UD[0]
LCD_LP	P7_6	LCDLP	P7_6	LCDLP	P7_6	LCDLP
LCD_ENAB/ LCDM	P4_6	LCDENAB/ LCDM	P4_6	LCDENAB/ LCDM	P4_6	LCDENAB/ LCDM
LCD_FP	P4_5	LCDFP	P4_5	LCDFP	P4_5	LCDFP
LCD_DCLK	P4_7	LCDDCLK	P4_7	LCDDCLK	P4_7	LCDDCLK
LCD_LE	P7_0	LCDLE	P7_0	LCDLE	P7_0	LCDLE
LCD_PWR	P7_7	LCDPWR	P7_7	LCDPWR	P7_7	LCDPWR
GP_CLKIN	PF_4	LCDCLKIN	PF_4	LCDCLKIN	PF_4	LCDCLKIN

Table 40. LCD panel connections for TFT panels

External pin	TFT 12 bit (4:4:4 mode)		TFT 16 bit (5:6:5 mode)		TFT 16 bit (1:5:5:5 mode)		TFT 24 bit	
	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function	LPC43xx pin used	LCD function
LCD_VD23	PB_0	BLUE3	PB_0	BLUE4	PB_0	BLUE4	PB_0	BLUE7
LCD_VD22	PB_1	BLUE2	PB_1	BLUE3	PB_1	BLUE3	PB_1	BLUE6
LCD_VD21	PB_2	BLUE1	PB_2	BLUE2	PB_2	BLUE2	PB_2	BLUE5
LCD_VD20	PB_3	BLUE0	PB_3	BLUE1	PB_3	BLUE1	PB_3	BLUE4
LCD_VD19	-	-	P7_1	BLUE0	P7_1	BLUE0	P7_1	BLUE3
LCD_VD18	-	-	-	-	P7_2	intensity	P7_2	BLUE2
LCD_VD17	-	-	-	-	-	-	P7_3	BLUE1
LCD_VD16	-	-	-	-	-	-	P7_4	BLUE0
LCD_VD15	PB_4	GREEN3	PB_4	GREEN5	PB_4	GREEN4	PB_4	GREEN7
LCD_VD14	PB_5	GREEN2	PB_5	GREEN4	PB_5	GREEN3	PB_5	GREEN6
LCD_VD13	PB_6	GREEN1	PB_6	GREEN3	PB_6	GREEN2	PB_6	GREEN5
LCD_VD12	P8_3	GREEN0	P8_3	GREEN2	P8_3	GREEN1	P8_3	GREEN4
LCD_VD11	-	-	P4_9	GREEN1	P4_9	GREEN0	P4_9	GREEN3
LCD_VD10	-	-	P4_10	GREEN0	P4_10	intensity	P4_10	GREEN2
LCD_VD9	-	-	-	-	-	-	P4_8	GREEN1
LCD_VD8	-	-	-	-	-	-	P7_5	GREEN0
LCD_VD7	P8_4	RED3	P8_4	RED4	P8_4	RED4	P8_4	RED7
LCD_VD6	P8_5	RED2	P8_5	RED3	P8_5	RED3	P8_5	RED6
LCD_VD5	P8_6	RED1	P8_6	RED2	P8_6	RED2	P8_6	RED5
LCD_VD4	P8_7	RED0	P8_7	RED1	P8_7	RED1	P8_7	RED4
LCD_VD3	-	-	P4_2	RED0	P4_2	RED0	P4_2	RED3
LCD_VD2	-	-	-	-	P4_3	intensity	P4_3	RED2
LCD_VD1	-	-	-	-	-	-	P4_4	RED1

Table 41. Recommended values for $C_{X1/X2}$ in oscillation mode (crystal and external components parameters) low frequency mode *…continued*

Fundamental oscillation frequency	Maximum crystal series resistance R_S	External load capacitors C_{X1}, C_{X2}
12 MHz	< 160 Ω	18 pF, 18 pF
	< 160 Ω	39 pF, 39 pF
16 MHz	< 120 Ω	18 pF, 18 pF
	< 80 Ω	33 pF, 33 pF
20 MHz	<100 Ω	18 pF, 18 pF
	< 80 Ω	33 pF, 33 pF

Table 42. Recommended values for $C_{X1/X2}$ in oscillation mode (crystal and external components parameters) high frequency mode

Fundamental oscillation frequency	Maximum crystal series resistance R_S	External load capacitors C_{X1}, C_{x2}
15 MHz	< 80 Ω	18 pF, 18 pF
20 MHz	< 80 Ω	39 pF, 39 pF
	< 100 Ω	47 pF, 47 pF

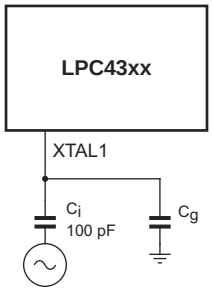


Fig 43. Slave mode operation of the on-chip oscillator

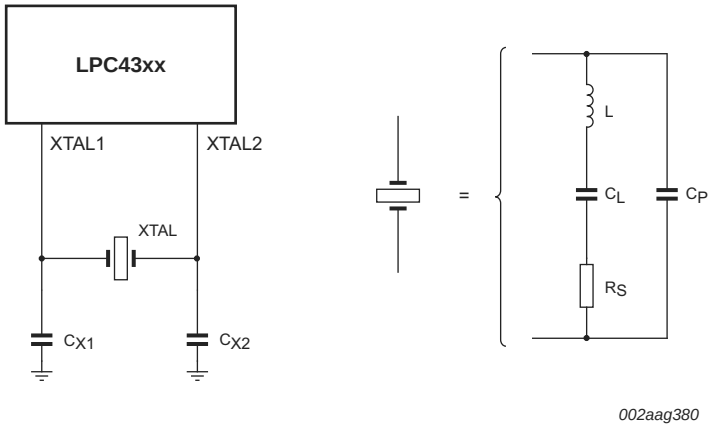


Fig 44. Oscillator modes with external crystal model used for C_{X1}/C_{X2} evaluation

13.3 RTC oscillator

In the RTC oscillator circuit, only the crystal (XTAL) and the capacitances C_{RTCX1} and C_{RTCX2} need to be connected externally. Typical capacitance values for C_{RTCX1} and C_{RTCX2} are $C_{RTCX1/2}$ = 20 (typical) $\pm$ 4 pF.

An external clock can be connected to RTCX1 if RTCX2 is left open. The recommended amplitude of the clock signal is $V_{i(RMS)}$ = 100 mV to 200 mV with a coupling capacitance of 5 pF to 10 pF. $V_{i(RMS)}$ must be lower than 450 mV. See Figure 43 for a similar slave-mode set-up that uses the crystal oscillator.

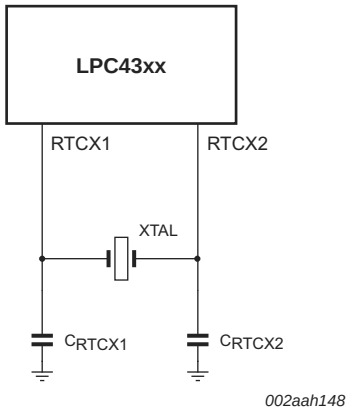


Fig 45. RTC 32 kHz oscillator circuit

13.4 XTAL and RTCX Printed Circuit Board (PCB) layout guidelines

Connect the crystal on the PCB as close as possible to the oscillator input and output pins of the chip. Take care that the load capacitors C_{x1}, C_{x2}, and C_{x3} in case of third overtone crystal usage have a common ground plane. Also connect the external components to the ground plain. To keep the noise coupled in via the PCB as small as possible, make loops and parasitics as small as possible. Choose smaller values of C_{x1} and C_{x2} if parasitics increase in the PCB layout.

Ensure that no high-speed or high-drive signals are near the RTCX1/2 signals.

13.5 Standard I/O pin configuration

Figure 46 shows the possible pin modes for standard I/O pins with analog input function:

- Digital output driver enabled/disabled
- Digital input: Pull-up enabled/disabled
- Digital input: Pull-down enabled/disabled
- Digital input: Repeater mode enabled/disabled
- Digital input: Input buffer enabled/disabled
- Analog input

The default configuration for standard I/O pins is input buffer disabled and pull-up enabled. The weak MOS devices provide a drive capability equivalent to pull-up and pull-down resistors.

16. Abbreviations

Table 43. Abbreviations

Acronym	Description
ADC	Analog-to-Digital Converter
AHB	Advanced High-performance Bus
APB	Advanced Peripheral Bus
API	Application Programming Interface
BOD	BrownOut Detection
CAN	Controller Area Network
CMAC	Cipher-based Message Authentication Code
CSMA/CD	Carrier Sense Multiple Access with Collision Detection
DAC	Digital-to-Analog Converter
DC-DC	Direct Current-to-Direct Current
DMA	Direct Memory Access
GPIO	General-Purpose Input/Output
IRC	Internal RC
IrDA	Infrared Data Association
JTAG	Joint Test Action Group
LCD	Liquid Crystal Display
LSB	Least Significant Bit
MAC	Media Access Control
MCU	MicroController Unit
MIIM	Media Independent Interface Management
n.c.	not connected
OHCI	Open Host Controller Interface
OTG	On-The-Go
PHY	Physical Layer
PLL	Phase-Locked Loop
PMC	Power Mode Control
PWM	Pulse Width Modulator
RIT	Repetitive Interrupt Timer
RMII	Reduced Media Independent Interface
SDRAM	Synchronous Dynamic Random Access Memory
SIMD	Single Instruction Multiple Data
SPI	Serial Peripheral Interface
SSI	Serial Synchronous Interface
SSP	Synchronous Serial Port
UART	Universal Asynchronous Receiver/Transmitter
ULPI	UTMI+ Low Pin Interface
USART	Universal Synchronous Asynchronous Receiver/Transmitter
USB	Universal Serial Bus
UTMI	USB2.0 Transceiver Macrocell Interface